

# TMT 15<sup>®</sup> - Precipitating Silver from Rinse Water

## Case Study / Info 33 E

TMT 15<sup>®</sup> is widely used in various industries that produce liquid wastes containing heavy metals. The heavy metals are usually removed from the wastewater by precipitation and flocculation.

Individual examples demonstrate the effectiveness of treatment methods in practice, and should give anyone interested enough background to perform tests to check the suitability of TMT 15® for their own particular wastewater composition. We would be happy to provide TMT 15® in sample amounts. Our Application Technology department is also prepared to provide assistance in finding solutions.

#### Photographic rinse water / Silverthiosulfate complex

Treatment process:

- Collect 4 I of rinse water (10 mg Ag/I, 2 g Na<sub>2</sub>S<sub>2</sub>O<sub>3</sub> x 5 H<sub>2</sub>O/I, pH 3.7),
- adjust to pH 9 using 2.4 ml of 10% caustic soda
- within 25 minutes, add 0.26 ml of TMT 15<sup>®</sup> while stirring,
- add 2 ml ferric chloride solution (10 g Fe/l)
- add 20 ml of 0.1% strong cationic flocculation aid (such as Praestol 655 BC),
- adjust to pH 9 using 0.3 ml of 10% caustic soda
- stir rapidly for 1 minute, slowly for 15 minutes,
- separate brown-colored, coarsely flocculent precipitate by filtering.

The filtrate only contained 0.2 mg Ag/l

#### Remarks

TMT 15<sup>®</sup> requirement: 6.4 I TMT 15<sup>®</sup> per kg Silver (Ag) in rinse water.

For Silver precipitation, it is usually necessary to adjust the pH value to the range 7-10 after the required chemicals have been added. To some extent, the precipitation result and residual metal content is strongly dependent on the pH value, depending on the type and concentration of com-plexing agents.

E-mail: tmt@evonik.com

http://www.tmt15.com

http://www.tmt15.com



### **Available examples**

Heavy metal	Complexing agent	Branch
Copper (Cu)	Tetrammine	Printed circuit board Manufacture
Copper (Cu)	EDTA complex	Printed circuit board Manufacture
Cadmium (Cd)	Tetrammine	Electroplating
Silver (Ag)	Thiosulfate complex	Photografic rinse water
Silver (Ag)	Thiosulfate complex	Photografic concentrate
Mercury (Hg)	Chlorocomplex	Chemical industry
Nickel (Ni)	Polyamine complex	Electroplating
Lead (Pb)	Cataphoretic	Automotive industry
	electro-deposition of paint	
Copper (Cu) & Nickel (Ni)	Actual wastewater	Printed circuit board Manufacture
	Copper (Cu) Cadmium (Cd) Silver (Ag) Silver (Ag) Mercury (Hg) Nickel (Ni) Lead (Pb)	Copper (Cu)  Copper (Cu)  EDTA complex  Cadmium (Cd)  Tetrammine  Silver (Ag)  Thiosulfate complex  Silver (Ag)  Thiosulfate complex  Mercury (Hg)  Chlorocomplex  Nickel (Ni)  Polyamine complex  Lead (Pb)  Cataphoretic electro-deposition of paint

This information and all further technical advice are based on our present knowledge and experience. However, it implies no liability or other legal responsibility on our part, including with regard to existing third party intellectual property rights, especially patent rights. In particular, no warranty, whether express or implied, or guarantee of product properties in the legal sense is intended or implied. We reserve the right to make any changes according to technological progress or further developments. The customer is not released from the obligation to conduct careful inspection and testing of incoming goods. Performance of the product described herein should be verified by testing, which should be carried out only by qualified experts in the sole responsibility of a customer. Reference to trade names used by other companies is neither a recommendation, nor does it imply that similar products could not be used.